SHARP GP2W0004YP

# GP2W0004YP

### **■** Features

- 1. Compliant with IrDA1.0
- 2. Integrated package of transmitter/receiver. (9.21×3.76×height 2.71mm)
- 3. General purpose
- 4. Low dissipation current due to shut-down function (Dissipation current at shut-down mode:Max. 1.0μA)
- 5. Soldering reflow type
- 6. Shield type

### ■ Applications

- 1. Cellular phones, PHS
- 2. Personal information tools

■ Absolute Maximum Ratings

 $(T_a=25^{\circ}C)$ 

Parameter	Symbol	Rating	Unit
Supply voltage	V <sub>CC</sub>	0 to 6.0	V
LED Supply voltage	V <sub>LEDA</sub>	0 to 7.0	V
Forward current	$I_F$	50	mA
*1 Peak forward current	$I_{FM}$	600	mA
Operating temperature	Topr	-25 to +85	°C
Storage temperature	T <sub>stg</sub>	-25 to +85	°C
*2 Soldering temperature	$T_{sol}$	240	°C

<sup>\*1</sup> Pulse width 115.2kb/s, Duty ratio :3/16

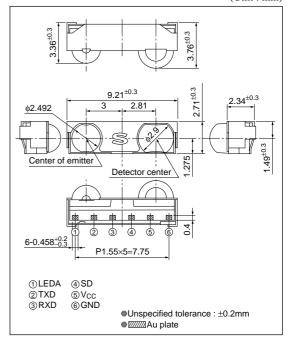
## **■** Recommended Operating Conditions

<u> </u>				
Parameter	Symbol	Rating	Unit	
Supply voltage	$V_{CC}$	2.4 to 5.5	V	
Transmission rate	BR	2.4 to 115.2	kb/s	
LED Supply Voltage	$V_{LEDA}$	2.4 to 7.0	V	
Operating temperature	Topr	-25 to +85	°C	

# IrDA Transceiver Module Compliant with IrDA1.0

### **■** Outline Dimensions

(Unit: mm)



<sup>\*2</sup> For MAX. 10s

mW/sr

nm

	Electrical Characteris	tics				(T <sub>a</sub> =25°C,	V <sub>CC</sub> =3.3V)
	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
	Dissipation current at no input signal	$I_{CC}$	No input light, output terminal open, V <sub>ILSD</sub> =0V	-	110	130	μΑ
	S/D dissipation current	I <sub>CC-S</sub>	No input light, output terminal open, $V_{IHSD}$ = $V_{CC}$	-	0.01	1.0	μΑ
	High level output voltage	$V_{OH1}$	V <sub>CC</sub> =5V, I <sub>OH</sub> =500μA	4.3	4.6	_	V
<u>e</u>		$V_{OH2}$	V <sub>CC</sub> =2.4V, I <sub>OH</sub> =500μA	1.5	1.7	-	V
Receiver side	Low level output voltage	V <sub>OL1</sub>	$V_{CC}=5V, I_{OL}=500\mu A^{*3}$	-	0.22	0.4	V
		$V_{OL2}$	$V_{CC}$ =2.4V, $I_{OL}$ =300 $\mu$ A*3	-	0.17	0.3	V
ece	Pules width	$t_{\rm w}$	BR=9.6kb/s, 115.2kb/s*3	1.0	2.4	3.6	μs
~	Rise time	t <sub>r</sub>	V <sub>CC</sub> =5.0V, C <sub>L</sub> =15pF	-	18	27	ns
	Fall time	$t_{\rm f}$	V <sub>CC</sub> =5.0V, C <sub>L</sub> =15pF	-	18	27	ns
	Maximum communication distance	L	V <sub>OH</sub> , V <sub>OL</sub> , tw, tr, tf *3 shall be satisfied at $\phi$ ≤15°	1	-	-	m

BR=115.2kb/s,  $\varphi \leq$  15°, Vleda=3.3V  $^{*4}$ 

40

850

870

900

Radiant intensity

Peak emission wavelength

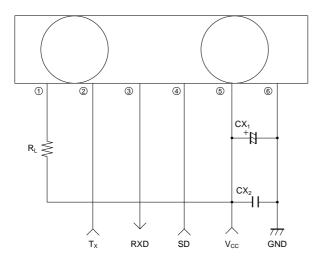
 $I_{\rm E}$ 

 $\lambda_{\rm p}$ 

Radiant int
Peak emiss
\*3 Refer to Fig. 3, 4, 5
\*4 Refer to Fig. 6, 7, 8

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Fig.1 Recommended External Circuit



Components circuit		Recommend values	
	CX <sub>1</sub>	*22µF	
	CX <sub>2</sub>	*0.1µF	
	Rı	(Table1)	

<sup>\*</sup> Please choose the most suitable CX<sub>1</sub> and CX<sub>2</sub> according to the noise level and noise frequency of power supply.

Table1					
VLED	R∟				
2.4≤VLED≤3.6V	0Ω±5%, 0.5W				
3.5≤VLED≤4.8V	1.3Ω±5%, 0.5W				
4.5<\/.ED<5.5\/	2.70+5% 0.5\\\				

① LEDA

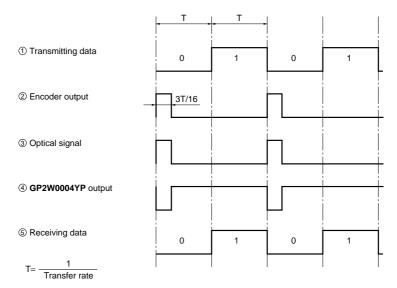
② TXD ③ RXD

4 SD

⑤ V<sub>CC</sub>

6 GND

Fig.2 Example of Signal Waveform



Transfer rate ; 2.4kb/s,9.6kb/s,19.2kb/s,38.4kb/s,57.6kb/s,115.2kb/s

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Fig.3 Input Signal Waveforrm(Receiver side)

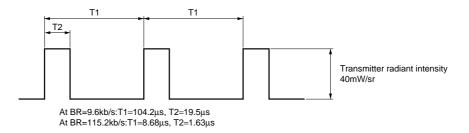


Fig.4 Output Waveform Specification (Receiver side)

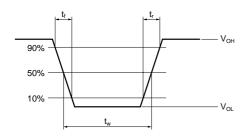
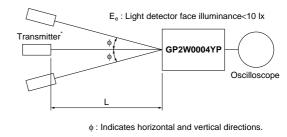
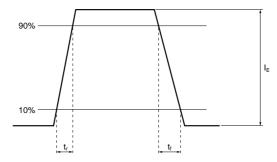


Fig.5 Standard Optical System (Receiver side)



\* Transmitter shall use **GP2W0004YP** (λp=870nm TYP.) which is adjusted the radiation intensity at 40mW/sr

Fig.6 Output Waveform Specification(Transmitter side)



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Fig.7 Standard Optical System(Transmitter side)

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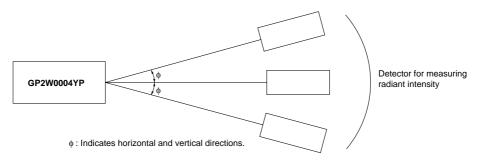


Fig.8 Recommended Circuit of Transmitter side

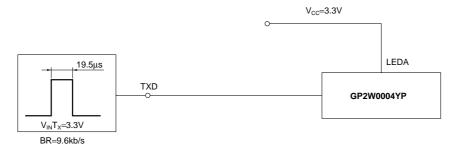
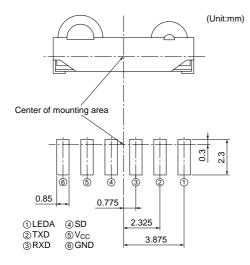


Fig.9 Recommended PCB Foot Pattern

Dimensions are shown for reference

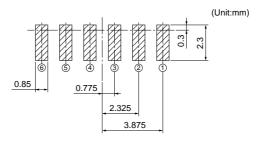


	Terminal	Symbol
1	LED anode	LEDA
2	Transmitter data input	TXD
3	Receiver data output	RXD
4	Shutdown	SD
⑤	Supply voltage	V <sub>cc</sub>
6	Ground	GND

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# Fig.10 Recommended Size of Solder Creamed Paste (Reference)

Please open the solder mask as below so that the size of solder creamed paste for this device before reflow soldering must be as large as one of the foot pattern land indicated Fig.9



Solder paste area

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